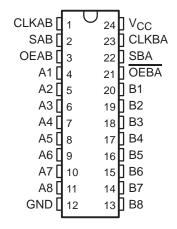
- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per **JESD 17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- High-Drive Outputs (-32-mA IOH, 64-mA IOI)
- **Multiplexed Real-Time and Stored Data**
- **Inverting Data Paths**
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

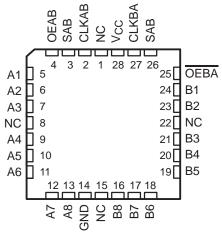
description

These devices consist of bus-transceiver circuits. D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. Output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. The select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. A low input level selects real-time data, and a high input level selects stored data. Figure 1 illustrates the four fundamental bus-management functions that performed with the 'ABT651 devices.





SN54ABT651 ... FK PACKAGE (TOP VIEW)



NC - No internal connection

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs, regardless of the select- or enable-control pins. When SAB and SBA are in the real-time transfer mode, it also is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all the other data sources to the two sets of bus lines are at high impedance, each set remains at its last state.

To ensure the high-impedance state during power up or power down, OEBA should be tied to VCC through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver (B to A). OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver (A to B).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated



SCBS083E - JANUARY 1991 - REVISED APRIL 1998

description (continued)

The SN54ABT651 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT651 is characterized for operation from -40° C to 85° C.

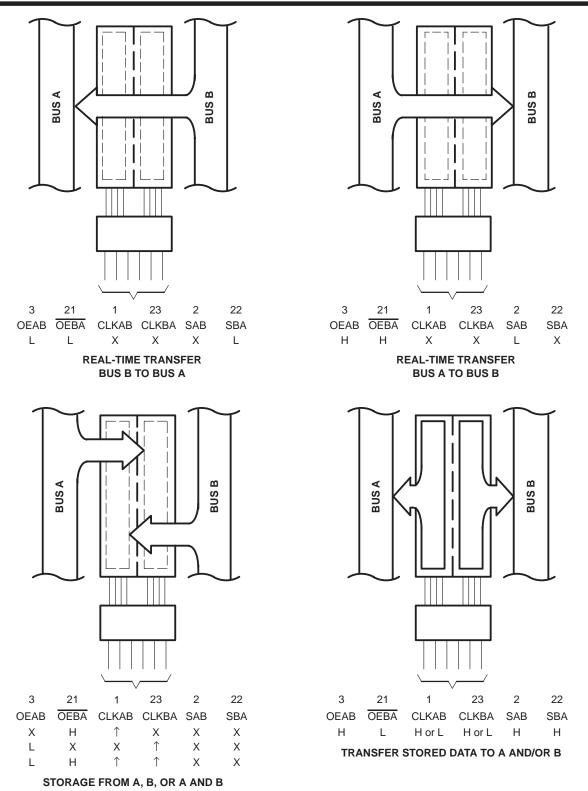
FUNCTION TABLE

		INPU ⁻	гѕ			DAT	A I/O	OPERATION OR FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation
L	Н	\uparrow	1	X	X	Input	Input	Store A and B data
Х	Н	1	H or L	Х	Х	Input	Unspecified [†]	Store A, hold B
Н	Н	\uparrow	\uparrow	X‡	X	Input	Output	Store A in both registers
L	Х	H or L	1	Х	Х	Unspecified [†]	Input	Hold A, store B
L	L	\uparrow	\uparrow	X	X‡	Output	Input	Store B in both registers
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	X	Н	Output	Input	Stored \overline{B} data to A bus
Н	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
Н	Н	H or L	Χ	Н	X	Input	Output	Stored \overline{A} data to B bus
Н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus

[†] The data output functions may be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



[‡] When select control is low, clocks can occur simultaneously if allowances are made for propagation delays from A to B (B to A) plus setup and hold times. When select control is high, clocks must be staggered to load both registers.



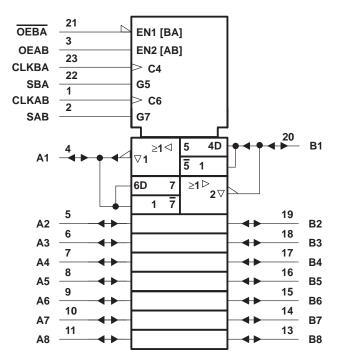
Pin numbers are for the DB, DW, JT, NT, and PW packages.

Figure 1. Bus-Management Functions



SCBS083E - JANUARY 1991 - REVISED APRIL 1998

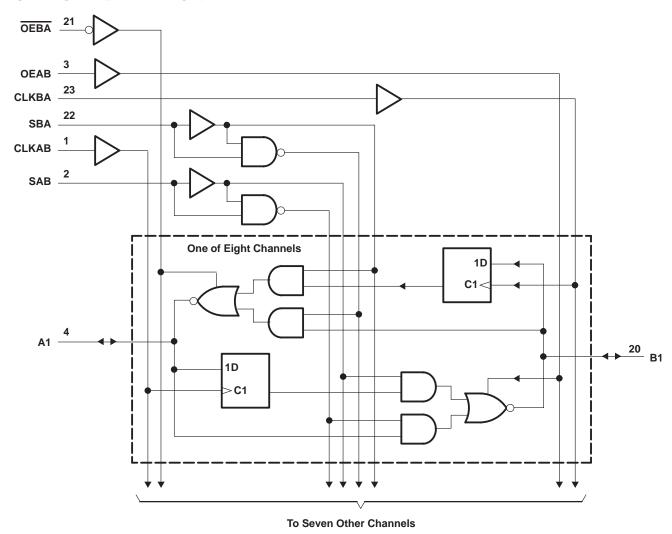
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, and PW packages.



logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, and PW packages.

SCBS083E - JANUARY 1991 - REVISED APRIL 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off sta	ate, V _O –0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT651	96 mA
SN74ABT651	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	104°C/W
DW package	81°C/W
NT package	67°C/W
PW package .	120°C/W
Storage temperature range, T _{sta}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54A	BT651	SN74A	BT651	UNIT
		MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	EM	2		V
VIL	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0 <	Vcc	0	VCC	V
loh	High-level output current	Ç)	-24		-32	mA
loL	Low-level output current	200	48		64	mA
Δt/Δν	Input transition rise or fall rate	S. D.	5		5	ns/V
TA	Operating free-air temperature	– 55	125	-40	85	°C

NOTE 3: All unused pins (control or I/O) of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	IDITIONS	Т	A = 25°C	;	SN54A	BT651	SN74A	BT651	UNIT
PARAMETER	TEST CON	ADITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII
VIK	V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\/a	$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH	V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				v
	VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V
VOL	VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$			0.55*				0.55	V
V _{hys}				100			4			mV
Control inputs	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		<u></u> ±1		±1	μΑ
A or B ports	VCC = 3.5 V,	1 = 100 01 014D			±100		±100		±100	μΑ
lozh [‡]	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 \text{ V}$			50		50		50	μΑ
l _{OZL} ‡	$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			-50	S	-50		-50	μΑ
l _{off}	$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100	0			±100	μΑ
ICEX	V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50	40	50		50	μА
IO§	V _{CC} = 5.5 V,	$V_0 = 2.5 \text{ V}$	-50	-100	-180	-50	-180	-50	-180	mA
	V _{CC} = 5.5 V,	Outputs high			250		250		250	μΑ
Icc	$I_{O} = 0$,	Outputs low			30		30		30	mA
	$V_I = V_{CC}$ or GND	Outputs disabled			250		250		250	μΑ
ΔICC¶	$V_{CC} = 5.5 \text{ V}$, One input Other inputs at V_{CC} of				1.5		1.5		1.5	mA
C _i Control inputs	V _I = 2.5 V or 0.5 V			6						pF
C _{io} A or B ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$			7.5						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		V _{CC} :	$V_{CC} = 5 V$, $T_A = 25^{\circ}C$		BT651	SN74AI	BT651	UNIT
		MIN MAX		MIN	MAX	MIN	MAX	
fclock	Clock frequency		125		125		125	MHz
t _W	Pulse duration, CLK high or low	4		4	10,71	4		ns
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3	71.	3		ns
t _h	Hold time, A or B after CLKAB↑ or CLKBA↑	0		0		0		ns

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $[\]P$ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

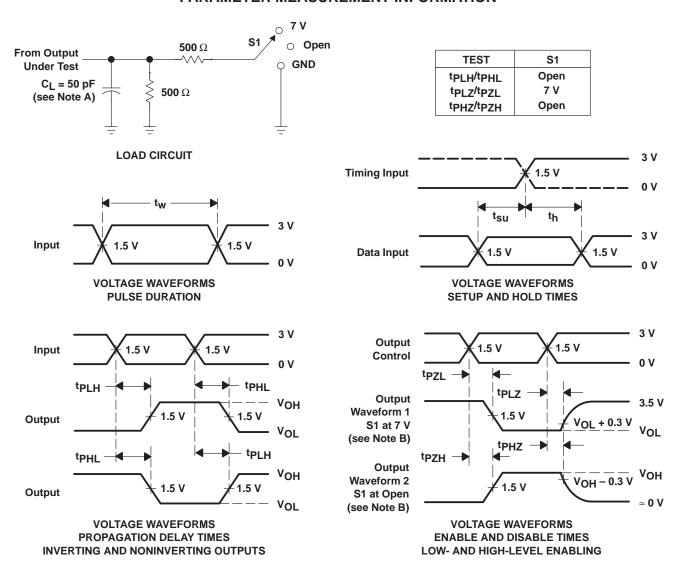
SCBS083E - JANUARY 1991 - REVISED APRIL 1998

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V(CC = 5 V A = 25°C	', ;	SN54A	BT651	SN74ABT651		UNIT	
	(INFOT)	(0011-01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX		
f _{max}			125			125		125		MHz	
^t PLH	CLKBA or CLKAB	A or B	2.2	4	5.1	2.2	5.9	2.2	5.6	ns	
^t PHL	CENDA OI CENAD	AUB	1.7	4	5.1	1.7	5.9	1.7	5.6	115	
^t PLH	A or B	B or A	1.5	4	5.1	1.5	6.4	1.5	6.2	ns	
^t PHL	AOID	BULA	1.5	3.3	4.6	1.5	5.6	1.5	5.4	113	
t _{PLH}	SAB or SBA†	A or B	1.5	4	5.1	1.5	6.8	1.5	6.5	ns	
t _{PHL}		7010	1.5	3.6	4.9	1.5	6.2	1.5	5.9	113	
^t PZH	OEBA	А	1.3	3.6	4.6	1.3	5.9	1.3	5.8	ns	
t _{PZL}	OEBA	A	2.5	5.7	6.8	2.5	8.9	2.5	8.5] 115	
^t PHZ	OEBA	А	1.5	3.2	4.5	01.5	6.2	1.5	5	ns	
^t PLZ	OEBA	٨	1.5	3	3.8	1.5	4.3	1.5	4.1	113	
^t PZH	OEAB	В	1.8	4.3	6.1	1.8	6.7	1.8	6.5	ns	
t _{PZL}	OLAB	В	2.9	5.5	6.5	2.9	7.6	2.9	7.4	115	
^t PHZ	OEAB	В	1.5	3.3	4.5	1.5	6.5	1.5	5.5	ns	
^t PLZ	OLAB	D D	1.5	3.4	4.4	1.5	5.2	1.5	5.1		

[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

www.ti.com 11-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
SN74ABT651DW	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT651
SN74ABT651DW.B	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT651
SN74ABT651DWR	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT651
SN74ABT651DWR.B	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT651

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

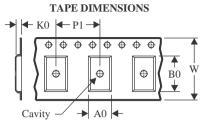
⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

www.ti.com 23-May-2025

TAPE AND REEL INFORMATION





_	<u> </u>
A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

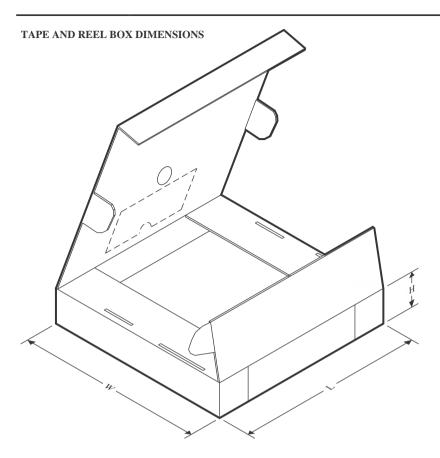


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT651DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 23-May-2025



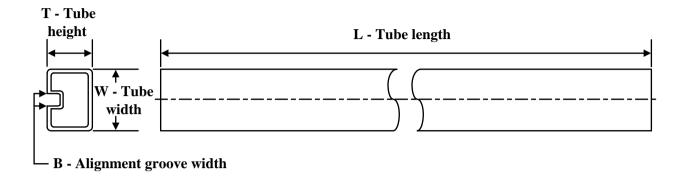
*All dimensions are nominal

Г	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
Г	SN74ABT651DWR	SOIC	DW	24	2000	350.0	350.0	43.0

PACKAGE MATERIALS INFORMATION

www.ti.com 23-May-2025

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABT651DW	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74ABT651DW.B	DW	SOIC	24	25	506.98	12.7	4826	6.6

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale, TI's General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025